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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	3328
Number of Logic Elements/Cells	29952
Total RAM Bits	589824
Number of I/O	221
Number of Gates	1500000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	320-BGA
Supplier Device Package	320-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s1500-4fgg320c

Table 4: Example Ordering Information

Device	Speed Grade		Package Type/Number of Pins		Temperature Range (T _j)	
XC3S50	-4	Standard Performance	VQ(G)100	100-pin Very Thin Quad Flat Pack (VQFP)	C	Commercial (0°C to 85°C)
XC3S200	-5	High Performance ⁽¹⁾	CP(G)132 ⁽²⁾	132-pin Chip-Scale Package (CSP)	I	Industrial (–40°C to 100°C)
XC3S400			TQ(G)144	144-pin Thin Quad Flat Pack (TQFP)		
XC3S1000			PQ(G)208	208-pin Plastic Quad Flat Pack (PQFP)		
XC3S1500			FT(G)256	256-ball Fine-Pitch Thin Ball Grid Array (FTBGA)		
XC3S2000			FG(G)320	320-ball Fine-Pitch Ball Grid Array (FBGA)		
XC3S4000			FG(G)456	456-ball Fine-Pitch Ball Grid Array (FBGA)		
XC3S5000			FG(G)676	676-ball Fine-Pitch Ball Grid Array (FBGA)		
			FG(G)900	900-ball Fine-Pitch Ball Grid Array (FBGA)		
			FG(G)1156 ⁽²⁾	1156-ball Fine-Pitch Ball Grid Array (FBGA)		

Notes:

1. The -5 speed grade is exclusively available in the Commercial temperature range.
2. The CP132, CPG132, FG1156, and FGG1156 packages are discontinued. See http://www.xilinx.com/support/documentation/spartan-3_customer_notices.htm.

Revision History

Date	Version	Description
04/11/03	1.0	Initial Xilinx release.
04/24/03	1.1	Updated block RAM, DCM, and multiplier counts for the XC3S50.
12/24/03	1.2	Added the FG320 package.
07/13/04	1.3	Added information on Pb-free packaging options.
01/17/05	1.4	Referenced Spartan-3 XA Automotive FPGA families in Table 1. Added XC3S50CP132, XC3S2000FG456, XC3S4000FG676 options to Table 3. Updated Package Marking to show mask revision code, fabrication facility code, and process technology code.
08/19/05	1.5	Added package markings for BGA packages (Figure 3) and CP132/CPG132 packages (Figure 4). Added differential (complementary single-ended) HSTL and SSTL I/O standards.
04/03/06	2.0	Increased number of supported single-ended and differential I/O standards.
04/26/06	2.1	Updated document links.
05/25/07	2.2	Updated Package Marking to allow for dual-marking.
11/30/07	2.3	Added XC3S5000 FG(G)676 to Table 3. Noted that FG(G)1156 package is being discontinued and updated max I/O count.
06/25/08	2.4	Updated max I/O counts based on FG1156 discontinuation. Clarified dual mark in Package Marking. Updated formatting and links.
12/04/09	2.5	CP132 and CPG132 packages are being discontinued. Added link to Spartan-3 FPGA customer notices. Updated Table 3 with package footprint dimensions.
10/29/12	3.0	Added Notice of Disclaimer section. Per XCN07022, updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011, updated the discontinued CP132 and CPG132 package discussion throughout document. Although the package is discontinued, updated the marking on Figure 4. This product is not recommended for new designs.



Spartan-3 FPGA Design Documentation

The functionality of the Spartan®-3 FPGA family is described in the following documents. The topics covered in each guide are listed.

- [UG331: Spartan-3 Generation FPGA User Guide](#)

- Clocking Resources
- Digital Clock Managers (DCMs)
- Block RAM
- Configurable Logic Blocks (CLBs)
 - Distributed RAM
 - SRL16 Shift Registers
 - Carry and Arithmetic Logic
- I/O Resources
- Embedded Multiplier Blocks
- Programmable Interconnect
- ISE® Software Design Tools
- IP Cores
- Embedded Processing and Control Solutions
- Pin Types and Package Overview
- Package Drawings
- Powering FPGAs

- [UG332: Spartan-3 Generation Configuration User Guide](#)

- Configuration Overview
 - Configuration Pins and Behavior
 - Bitstream Sizes
- Detailed Descriptions by Mode
 - Master Serial Mode using Xilinx Platform Flash PROM
 - Slave Parallel (SelectMAP) using a Processor
 - Slave Serial using a Processor
 - JTAG Mode
- ISE iMPACT Programming Examples

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For specific hardware examples, see the Spartan-3 FPGA Starter Kit board web page, which has links to various design examples and the user guide.

- Spartan-3 FPGA Starter Kit Board page

<http://www.xilinx.com/s3starter>

- [UG130: Spartan-3 FPGA Starter Kit User Guide](#)

Supply Voltages for the IOBs

Three different supplies power the IOBs:

- The V_{CCO} supplies, one for each of the FPGA's I/O banks, power the output drivers, except when using the GTL and GTLP signal standards. The voltage on the V_{CCO} pins determines the voltage swing of the output signal.
- V_{CCINT} is the main power supply for the FPGA's internal logic.
- The V_{CCAUX} is an auxiliary source of power, primarily to optimize the performance of various FPGA functions such as I/O switching.

The I/Os During Power-On, Configuration, and User Mode

With no power applied to the FPGA, all I/Os are in a high-impedance state. The V_{CCINT} (1.2V), V_{CCAUX} (2.5V), and V_{CCO} supplies may be applied in any order. Before power-on can finish, V_{CCINT} , V_{CCO} Bank 4, and V_{CCAUX} must have reached their respective minimum recommended operating levels (see [Table 29, page 59](#)). At this time, all I/O drivers also will be in a high-impedance state. V_{CCO} Bank 4, V_{CCINT} , and V_{CCAUX} serve as inputs to the internal Power-On Reset circuit (POR).

A Low level applied to the HSWAP_EN input enables pull-up resistors on User I/Os from power-on throughout configuration. A High level on HSWAP_EN disables the pull-up resistors, allowing the I/Os to float. If the HSWAP_EN pin is floating, then an internal pull-up resistor pulls HSWAP_EN High. As soon as power is applied, the FPGA begins initializing its configuration memory. At the same time, the FPGA internally asserts the Global Set-Reset (GSR), which asynchronously resets all IOB storage elements to a Low state.

Upon the completion of initialization, INIT_B goes High, sampling the M0, M1, and M2 inputs to determine the configuration mode. At this point, the configuration data is loaded into the FPGA. The I/O drivers remain in a high-impedance state (with or without pull-up resistors, as determined by the HSWAP_EN input) throughout configuration.

The Global Three State (GTS) net is released during Start-Up, marking the end of configuration and the beginning of design operation in the User mode. At this point, those I/Os to which signals have been assigned go active while all unused I/Os remain in a high-impedance state. The release of the GSR net, also part of Start-up, leaves the IOB registers in a Low state by default, unless the loaded design reverses the polarity of their respective RS inputs.

In User mode, all internal pull-up resistors on the I/Os are disabled and HSWAP_EN becomes a “don't care” input. If it is desirable to have pull-up or pull-down resistors on I/Os carrying signals, the appropriate symbol—e.g., PULLUP, PULLDOWN—must be placed at the appropriate pads in the design. The Bitstream Generator (Bitgen) option UnusedPin available in the Xilinx development software determines whether unused I/Os collectively have pull-up resistors, pull-down resistors, or no resistors in User mode.

CLB Overview

For more details on the CLBs, refer to the chapter entitled “Using Configurable Logic Blocks” in [UG331](#).

The Configurable Logic Blocks (CLBs) constitute the main logic resource for implementing synchronous as well as combinatorial circuits. Each CLB comprises four interconnected slices, as shown in [Figure 11](#). These slices are grouped in pairs. Each pair is organized as a column with an independent carry chain.

The nomenclature that the FPGA Editor—part of the Xilinx development software—uses to designate slices is as follows: The letter ‘X’ followed by a number identifies columns of slices. The ‘X’ number counts up in sequence from the left side of the die to the right. The letter ‘Y’ followed by a number identifies the position of each slice in a pair as well as indicating the CLB row. The ‘Y’ number counts slices starting from the bottom of the die according to the sequence: 0, 1, 0, 1 (the first CLB row); 2, 3, 2, 3 (the second CLB row); etc. [Figure 11](#) shows the CLB located in the lower left-hand corner of the die. Slices X0Y0 and X0Y1 make up the column-pair on the left where as slices X1Y0 and X1Y1 make up the column-pair on the right. For each CLB, the term “left-hand” (or SLICEM) indicates the pair of slices labeled with an even ‘X’ number, such as X0, and the term “right-hand” (or SLICEL) designates the pair of slices with an odd ‘X’ number, e.g., X1.

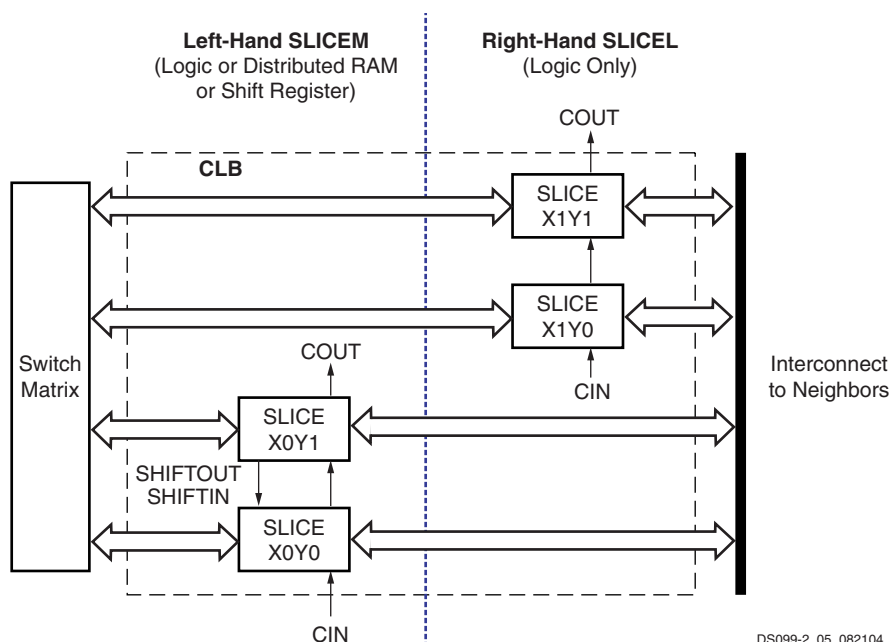


Figure 11: Arrangement of Slices within the CLB

Elements Within a Slice

All four slices have the following elements in common: two logic function generators, two storage elements, wide-function multiplexers, carry logic, and arithmetic gates, as shown in [Figure 12, page 24](#). Both the left-hand and right-hand slice pairs use these elements to provide logic, arithmetic, and ROM functions. Besides these, the left-hand pair supports two additional functions: storing data using Distributed RAM and shifting data with 16-bit registers. [Figure 12](#) is a diagram of the left-hand slice; therefore, it represents a superset of the elements and connections to be found in all slices. See [Function Generator, page 25](#) for more information.

The RAM-based function generator—also known as a Look-Up Table or LUT—is the main resource for implementing logic functions. Furthermore, the LUTs in each left-hand slice pair can be configured as Distributed RAM or a 16-bit shift register. For information on the former, refer to the chapter entitled “Using Look-Up Tables as Distributed RAM” in [UG331](#); for information on the latter, refer to the chapter entitled “Using Look-Up Tables as Shift Registers” in [UG331](#). The function generators located in the upper and lower portions of the slice are referred to as the “G” and “F”, respectively.

The storage element, which is programmable as either a D-type flip-flop or a level-sensitive latch, provides a means for synchronizing data to a clock signal, among other uses. The storage elements in the upper and lower portions of the slice are called FFY and FFX, respectively.

Wide-function multiplexers effectively combine LUTs in order to permit more complex logic operations. Each slice has two of these multiplexers with F5MUX in the lower portion of the slice and F1MUX in the upper portion. Depending on the slice, F1MUX takes on the name F6MUX, F7MUX, or F8MUX. For more details on the multiplexers, refer to the chapter entitled “Using Dedicated Multiplexers” in [UG331](#).

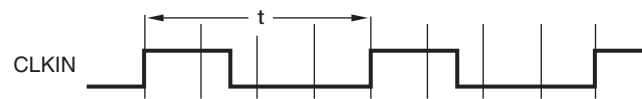
The carry chain, together with various dedicated arithmetic logic gates, support fast and efficient implementations of math operations. The carry chain enters the slice as CIN and exits as COUT. Five multiplexers control the chain: CYINIT, CY0F, and CYMUXF in the lower portion as well as CY0G and CYMUXG in the upper portion. The dedicated arithmetic logic includes the exclusive-OR gates XORG and XORF (upper and lower portions of the slice, respectively) as well as the AND gates GAND and FAND (upper and lower portions, respectively). For more details on the carry logic, refer to the chapter entitled “Using Carry and Arithmetic Logic” in [UG331](#).

Main Logic Paths

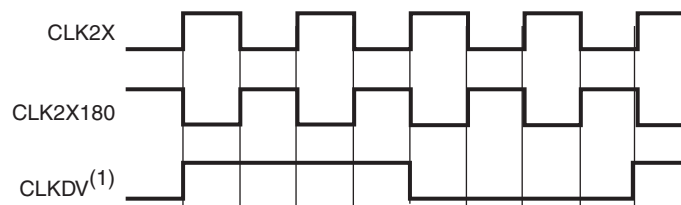
Central to the operation of each slice are two nearly identical data paths, distinguished using the terms *top* and *bottom*. The description that follows uses names associated with the bottom path. (The top path names appear in parentheses.) The basic path originates at an interconnect-switch matrix outside the CLB. Four lines, F1 through F4 (or G1 through G4 on the

Phase: 0° 90° 180° 270° 0° 90° 180° 270° 0°

Input Signal (40% Duty Cycle)

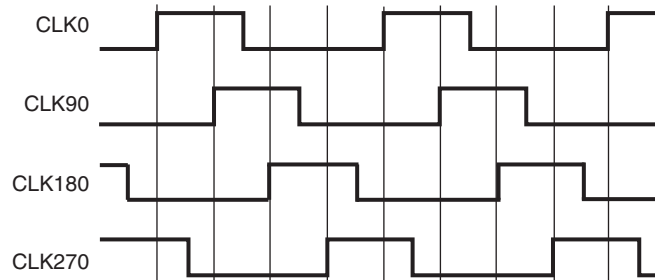


Output Signal - Duty Cycle is Always Corrected

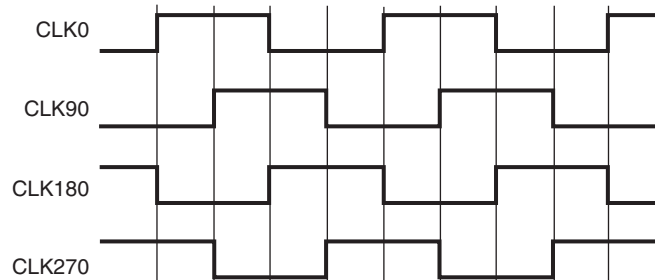


Output Signal - Attribute Corrects Duty Cycle

DUTY_CYCLE_CORRECTION = FALSE



DUTY_CYCLE_CORRECTION = TRUE



DS099-2_10_051907

Figure 22: Characteristics of the DLL Clock Outputs

Digital Frequency Synthesizer (DFS)

The DFS component generates clock signals the frequency of which is a product of the clock frequency at the CLKIN input and a ratio of two user-determined integers. Because of the wide range of possible output frequencies such a ratio permits, the DFS feature provides still further flexibility than the DLL's basic synthesis options as described in the preceding section. The DFS component's two dedicated outputs, CLKFX and CLKFX180, are defined in Table 19.

The signal at the CLKFX180 output is essentially an inversion of the CLKFX signal. These two outputs always exhibit a 50% duty cycle. This is true even when the CLKIN signal does not. These DFS clock outputs are driven at the same time as the DLL's seven clock outputs.

The numerator of the ratio is the integer value assigned to the attribute CLKFX_MULTIPLY and the denominator is the integer value assigned to the attribute CLKFX_DIVIDE. These attributes are described in Table 18.

The Standard Configuration Interface

Configuration signals belong to one of two different categories: Dedicated or Dual-Purpose. Which category determines which of the FPGA's power rails supplies the signal's driver and, thus, helps describe the electrical characteristics at the pin.

The Dedicated configuration pins include PROG_B, HSWAP_EN, TDI, TMS, TCK, TDO, CCLK, DONE, and M0-M2. These pins are powered by the V_{CCAUX} supply.

The Dual-Purpose configuration pins comprise INIT_B, DOUT, BUSY, RDWR_B, CS_B, and DIN/D0-D7. Each of these pins, according to its bank placement, uses the V_{CCO} lines for either Bank 4 (V_{CCO_4} on most packages, V_{CCO_BOTTOM} on TQ144 and CP132 packages) or Bank 5 (V_{CCO_5}). All the signals used in the serial configuration modes rely on V_{CCO_4} power. Signals used in the parallel configuration modes and Readback require from V_{CCO_5} as well as from V_{CCO_4} .

Both the Dedicated signals described above and the Dual-Purpose signals constitute the configuration interface. The Dedicated pins, powered by the 2.5V V_{CCAUX} supply, always use the LVCMOS25 I/O standard. The Dual-Purpose signals, however, are powered by the V_{CCO_4} supply and also by the V_{CCO_5} supply in the Parallel configuration modes. The simplest configuration interface uses 2.5V for V_{CCO_4} and V_{CCO_5} , if required. However, V_{CCO_4} and, if needed, V_{CCO_5} can be voltages other than 2.5V but then the configuration interface will have two voltage levels: 2.5V for V_{CCAUX} and a separate V_{CCO} supply. The Dual-Purpose signals default to the LVCMOS input and output levels for the associated V_{CCO} voltage supply.

3.3V-Tolerant Configuration Interface

A 3.3V-tolerant configuration interface simply requires adding a few external resistors as described in detail in [XAPP453: The 3.3V Configuration of Spartan-3 FPGAs](#).

The 3.3V-tolerance is implemented as follows (a similar approach can be used for other supply voltage levels):

Apply 3.3V to V_{CCO_4} and, in some configuration modes, to V_{CCO_5} to power the Dual-Purpose configuration pins. This scales the output voltages and input thresholds associated with these pins so that they become 3.3V-compatible.

Apply 2.5V to V_{CCAUX} to power the Dedicated configuration pins. For 3.3V-tolerance, the Dedicated inputs require series resistors to limit the incoming current to 10 mA or less. The Dedicated outputs have reduced noise margin when the FPGA drives a High logic level into another device's 3.3V receiver. Choose a power regulator or supply that can tolerate reverse current on the V_{CCAUX} lines.

Configuration Modes

Spartan-3 FPGAs support the following five configuration modes:

- Slave Serial mode
- Master Serial mode
- Slave Parallel (SelectMAP) mode
- Master Parallel (SelectMAP) mode
- Boundary-Scan (JTAG) mode (IEEE 1532/IEEE 1149.1)

Slave Serial Mode

In Slave Serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other serial source of configuration data. The FPGA on the far right of [Figure 26](#) is set for the Slave Serial mode. The CCLK pin on the FPGA is an input in this mode. The serial bitstream must be set up at the DIN input pin a short time before each rising edge of the externally generated CCLK.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed internally to the DOUT pin. The data on the DOUT pin changes on the falling edge of CCLK.

Revision History

Date	Version No.	Description
04/11/03	1.0	Initial Xilinx release
05/19/03	1.1	Added Block RAM column, DCMs, and multipliers to XC3S50 descriptions.
07/11/03	1.2	Explained the configuration port <i>Persist</i> option in Slave Parallel Mode (SelectMAP) section. Updated Figure 8 and Double-Data-Rate Transmission section to indicate that DDR clocking for the XC3S50 is the same as that for all other Spartan-3 devices. Updated description of I/O voltage tolerance in ESD Protection section. In Table 10 , changed input termination type for DCI version of the LVCMOS standard to <i>None</i> . Added additional flexibility for making DLL connections in Figure 21 and accompanying text. In the Configuration section, inserted an explanation of how to choose power supplies for the configuration interface, including guidelines for achieving 3.3V-tolerance.
08/24/04	1.3	Showed inversion of 3-state signal (Figure 7). Clarified description of pull-up and pull-down resistors (Table 6 and page 13). Added information on operating block RAM with multipliers to page 26 . Corrected output buffer name in Figure 21 . Corrected description of how DOUT is synchronized to CCLK (page 47).
08/19/05	1.4	Corrected description of WRITE_FIRST and READ_FIRST in Table 13 . Added note regarding address setup and hold time requirements whenever a block RAM port is enabled (Table 13). Added information in the maximum length of a Configuration daisy-chain. Added reference to XAPP453 in 3.3V-Tolerant Configuration Interface section. Added information on the STATUS[2] DCM output (Table 23). Added information on CCLK behavior and termination recommendations to Configuration . Added Additional Configuration Details section. Added Powering Spartan-3 FPGAs section. Removed GSR from Figure 31 because its timing is not programmable.
04/03/06	2.0	Updated Figure 7 . Updated Figure 14 . Updated Table 10 . Updated Figure 22 . Corrected Platform Flash supply voltage name and value in Figure 26 and Figure 28 . Added No Internal Charge Pumps or Free-Running Oscillators . Corrected a few minor typographical errors.
04/26/06	2.1	Added more information on the pull-up resistors that are active during configuration to Configuration . Added information to Boundary-Scan (JTAG) Mode about potential interactions when configuring via JTAG if the mode select pins are set for other than JTAG.
05/25/07	2.2	Added Spartan-3 FPGA Design Documentation . Noted SSTL2_I_DCI 25-Ohm driver in Table 10 and Table 11 . Added note that pull-down is active during boundary scan tests.
11/30/07	2.3	Updated links to documentation on xilinx.com.
06/25/08	2.4	Added HSLVDCI to Table 10 . Updated formatting and links.
12/04/09	2.5	Updated HSLVDCI description in Digitally Controlled Impedance (DCI) . Updated the low-voltage differential signaling V_{CCO} values in Table 10 . Noted that the CP132 package is being discontinued in The Organization of IOBs into Banks . Updated rule 4 in Rules Concerning Banks . Added software version requirement in The Fixed Phase Mode .
10/29/12	3.0	Added Notice of Disclaimer . Per XCN07022 , updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011 , updated the discontinued CP132 and CPG132 package discussion throughout document. This product is not recommended for new designs.

Table 45: Timing for the IOB Output Path

Symbol	Description	Conditions	Device	Speed Grade		Units
				-5	-4	
				Max ⁽³⁾	Max ⁽³⁾	
Clock-to-Output Times						
T _{IOCKP}	When reading from the Output Flip-Flop (OFF), the time from the active transition at the OTCLK input to data appearing at the Output pin	LVCMOS25 ⁽²⁾ , 12 mA output drive, Fast slew rate	XC3S200 XC3S400	1.28	1.47	ns
			XC3S50 XC3S1000 XC3S1500 XC3S2000 XC3S4000 XC3S5000	1.95	2.24	ns
Propagation Times						
T _{IOOP}	The time it takes for data to travel from the IOB's O input to the Output pin	LVCMOS25 ⁽²⁾ , 12 mA output drive, Fast slew rate	XC3S200 XC3S400	1.28	1.46	ns
			XC3S50 XC3S1000 XC3S1500 XC3S2000 XC3S4000 XC3S5000	1.94	2.23	ns
T _{IOOLP}	The time it takes for data to travel from the O input through the OFF latch to the Output pin		XC3S200 XC3S400	1.28	1.47	ns
			XC3S50 XC3S1000 XC3S1500 XC3S2000 XC3S4000 XC3S5000	1.95	2.24	ns
Set/Reset Times						
T _{IOSRP}	Time from asserting the OFF's SR input to setting/resetting data at the Output pin	LVCMOS25 ⁽²⁾ , 12 mA output drive, Fast slew rate	XC3S200 XC3S400	2.10	2.41	ns
			XC3S50 XC3S1000 XC3S1500 XC3S2000 XC3S4000 XC3S5000	2.77	3.18	ns
T _{IOGSRQ}	Time from asserting the Global Set Reset (GSR) net to setting/resetting data at the Output pin		All	8.07	9.28	ns

Notes:

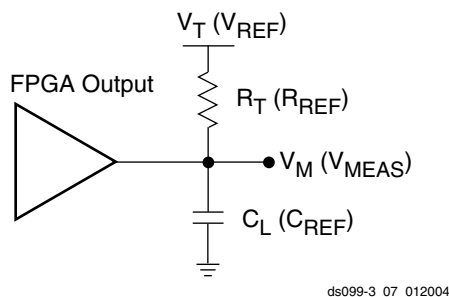
1. The numbers in this table are tested using the methodology presented in [Table 48](#) and are based on the operating conditions set forth in [Table 32](#) and [Table 35](#).
2. This time requires adjustment whenever a signal standard other than LVCMOS25 with 12 mA drive and Fast slew rate is assigned to the data Output. When this is true, *add* the appropriate Output adjustment from [Table 47](#).
3. For minimums, use the values reported by the Xilinx timing analyzer.

Timing Measurement Methodology

When measuring timing parameters at the programmable I/Os, different signal standards call for different test conditions. Table 48 presents the conditions to use for each standard.

The method for measuring Input timing is as follows: A signal that swings between a Low logic level of V_L and a High logic level of V_H is applied to the Input under test. Some standards also require the application of a bias voltage to the V_{REF} pins of a given bank to properly set the input-switching threshold. The measurement point of the Input signal (V_M) is commonly located halfway between V_L and V_H .

The Output test setup is shown in Figure 35. A termination voltage V_T is applied to the termination resistor R_T , the other end of which is connected to the Output. For each standard, R_T and V_T generally take on the standard values recommended for minimizing signal reflections. If the standard does not ordinarily use terminations (e.g., LVCMOS, LVTTTL), then R_T is set to 1M Ω to indicate an open connection, and V_T is set to zero. The same measurement point (V_M) that was used at the Input is also used at the Output.



Notes:

1. The names shown in parentheses are used in the IBIS file.

Figure 35: Output Test Setup

Table 48: Test Methods for Timing Measurement at I/Os

Signal Standard (IOSTANDARD)	Inputs			Outputs		Inputs and Outputs
	V_{REF} (V)	V_L (V)	V_H (V)	R_T (Ω)	V_T (V)	V_M (V)
Single-Ended						
GTL	0.8	$V_{REF} - 0.2$	$V_{REF} + 0.2$	25	1.2	V_{REF}
GTL_DCI				50	1.2	
GTLTP	1.0	$V_{REF} - 0.2$	$V_{REF} + 0.2$	25	1.5	V_{REF}
GTLTP_DCI				50	1.5	
HSLVDCI_15	0.9	$V_{REF} - 0.5$	$V_{REF} + 0.5$	1M	0	0.75
HSLVDCI_18						0.90
HSLVDCI_25						1.25
HSLVDCI_33						1.65
HSTL_I	0.75	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	0.75	V_{REF}
HSTL_I_DCI						
HSTL_III	0.90	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	1.5	V_{REF}
HSTL_III_DCI						
HSTL_I_18	0.90	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	0.9	V_{REF}
HSTL_I_DCI_18						
HSTL_II_18	0.90	$V_{REF} - 0.5$	$V_{REF} + 0.5$	50	0.9	V_{REF}
HSTL_II_DCI_18						

Table 48: Test Methods for Timing Measurement at I/Os (Cont'd)

Signal Standard (IOSTANDARD)		Inputs			Outputs		Inputs and Outputs
		V _{REF} (V)	V _L (V)	V _H (V)	R _T (Ω)	V _T (V)	V _M (V)
HSTL_III_18		1.1	V _{REF} − 0.5	V _{REF} + 0.5	50	1.8	V _{REF}
HSTL_III_DCI_18							
LVCMOS12		-	0	1.2	1M	0	0.6
LVCMOS15		-	0	1.5	1M	0	0.75
LVDCI_15							
LVDCI_DV2_15							
HSLVDCI_15							
LVCMOS18		-	0	1.8	1M	0	0.9
LVDCI_18							
LVDCI_DV2_18							
HSLVDCI_18							
LVCMOS25		-	0	2.5	1M	0	1.25
LVDCI_25							
LVDCI_DV2_25							
HSLVDCI_25							
LVCMOS33		-	0	3.3	1M	0	1.65
LVDCI_33							
LVDCI_DV2_33							
HSLVDCI_33							
LVTTTL		-	0	3.3	1M	0	1.4
PCI33_3	Rising	-	Note 3	Note 3	25	0	0.94
	Falling				25	3.3	2.03
SSTL18_I		0.9	V _{REF} − 0.5	V _{REF} + 0.5	50	0.9	V _{REF}
SSTL18_I_DCI							
SSTL18_II		0.9	V _{REF} − 0.5	V _{REF} + 0.5	50	0.9	V _{REF}
SSTL2_I		1.25	V _{REF} − 0.75	V _{REF} + 0.75	50	1.25	V _{REF}
SSTL2_I_DCI							
SSTL2_II		1.25	V _{REF} − 0.75	V _{REF} + 0.75	25	1.25	V _{REF}
SSTL2_II_DCI					50	1.25	
Differential							
LDT_25 (ULVDS_25)		-	V _{ICM} − 0.125	V _{ICM} + 0.125	60	0.6	V _{ICM}
LVDS_25		-	V _{ICM} − 0.125	V _{ICM} + 0.125	50	1.2	V _{ICM}
LVDS_25_DCI					N/A	N/A	
BLVDS_25		-	V _{ICM} − 0.125	V _{ICM} + 0.125	1M	0	V _{ICM}
LVDSEXT_25		-	V _{ICM} − 0.125	V _{ICM} + 0.125	50	1.2	V _{ICM}
LVDSEXT_25_DCI					N/A	N/A	
LVPECL_25		-	V _{ICM} − 0.3	V _{ICM} + 0.3	1M	0	V _{ICM}
RSDS_25		-	V _{ICM} − 0.1	V _{ICM} + 0.1	50	1.2	V _{ICM}
DIFF_HSTL_II_18		-	V _{ICM} − 0.5	V _{ICM} + 0.5	50	1.8	V _{ICM}
DIFF_HSTL_II_18_DCI							

Internal Logic Timing

Table 51: CLB Timing

Symbol	Description	Speed Grade				Units
		-5		-4		
		Min	Max	Min	Max	
Clock-to-Output Times						
T _{CKO}	When reading from the FFX (FFY) Flip-Flop, the time from the active transition at the CLK input to data appearing at the XQ (YQ) output	—	0.63	—	0.72	ns
Setup Times						
T _{AS}	Time from the setup of data at the F or G input to the active transition at the CLK input of the CLB	0.46	—	0.53	—	ns
T _{DICK}	Time from the setup of data at the BX or BY input to the active transition at the CLK input of the CLB	1.27	—	1.57	—	ns
Hold Times						
T _{AH}	Time from the active transition at the CLK input to the point where data is last held at the F or G input	0	—	0	—	ns
T _{CKDI}	Time from the active transition at the CLK input to the point where data is last held at the BX or BY input	0.25	—	0.29	—	ns
Clock Timing						
T _{CH}	CLB CLK signal High pulse width	0.69	∞	0.79	∞	ns
T _{CL}	CLB CLK signal Low pulse width	0.69	∞	0.79	∞	ns
F _{TOG}	Maximum toggle frequency (for export control)	—	725	—	630	MHz
Propagation Times						
T _{ILO}	The time it takes for data to travel from the CLB's F (G) input to the X (Y) output	—	0.53	—	0.61	ns
Set/Reset Pulse Width						
T _{RPW_CLB}	The minimum allowable pulse width, High or Low, to the CLB's SR input	0.76	—	0.87	—	ns

Notes:

1. The numbers in this table are based on the operating conditions set forth in [Table 32](#).
2. The timing shown is for SLICEM.
3. For minimums, use the values reported by the Xilinx timing analyzer.

Table 71: Dual-Purpose Pins Used in Master or Slave Serial Mode

Pin Name	Direction	Description
DIN	Input	Serial Data Input: During the Master or Slave Serial configuration modes, DIN is the serial configuration data input, and all data is synchronized to the rising CCLK edge. After configuration, this pin is available as a user I/O. This signal is located in Bank 4 and its output voltage determined by VCCO_4. The BitGen option Persist permits this pin to retain its configuration function in the User mode.
DOUT	Output	Serial Data Output: In a multi-FPGA design where all the FPGAs use serial mode, connect the DOUT output of one FPGA—in either Master or Slave Serial mode—to the DIN input of the next FPGA—in Slave Serial mode—so that configuration data passes from one to the next, in daisy-chain fashion. This “daisy chain” permits sequential configuration of multiple FPGAs. This signal is located in Bank 4 and its output voltage determined by VCCO_4. The BitGen option Persist permits this pin to retain its configuration function in the User mode.
INIT_B	Bidirectional (open-drain)	Initializing Configuration Memory/Configuration Error: Just after power is applied, the FPGA produces a Low-to-High transition on this pin indicating that initialization (<i>i.e.</i> , clearing) of the configuration memory has finished. Before entering the User mode, this pin functions as an open-drain output, which requires a pull-up resistor in order to produce a High logic level. In a multi-FPGA design, tie (wire AND) the INIT_B pins from all FPGAs together so that the common node transitions High only after all of the FPGAs have been successfully initialized. Externally holding this pin Low beyond the initialization phase delays the start of configuration. This action stalls the FPGA at the configuration step just before the mode select pins are sampled. During configuration, the FPGA indicates the occurrence of a data (<i>i.e.</i> , CRC) error by asserting INIT_B Low. This signal is located in Bank 4 and its output voltage determined by VCCO_4. The BitGen option Persist permits this pin to retain its configuration function in the User mode.

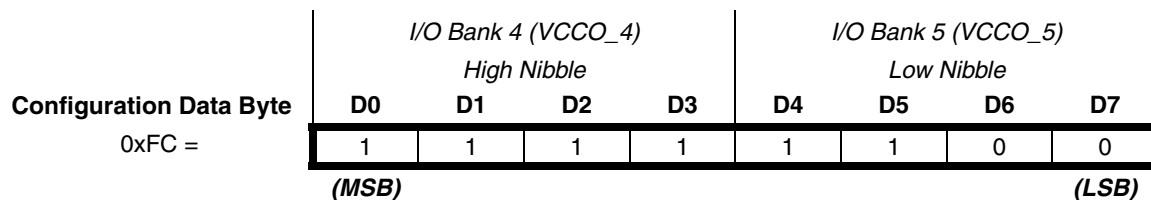


Figure 41: Configuration Data Byte Mapping to D0-D7 Bits

Parallel Configuration Modes (SelectMAP)

This section describes the dual-purpose configuration pins used during the Master and Slave Parallel configuration modes, sometimes also called the SelectMAP modes. In both Master and Slave Parallel configuration modes, D0-D7 form the byte-wide configuration data input. See Table 75 for Mode Select pin settings required for Parallel modes.

As shown in Figure 41, D0 is the most-significant bit while D7 is the least-significant bit. Bits D0-D3 form the high nibble of the byte and bits D4-D7 form the low nibble.

In the Parallel configuration modes, both the VCCO_4 and VCCO_5 voltage supplies are required and must both equal the voltage of the attached configuration device, typically either 2.5V or 3.3V.

Assert Low both the chip-select pin, CS_B, and the read/write control pin, RDWR_B, to write the configuration data byte presented on the D0-D7 pins to the FPGA on a rising-edge of the configuration clock, CCLK. The order of CS_B and RDWR_B does not matter, although RDWR_B must be asserted throughout the configuration process. If RDWR_B is de-asserted during configuration, the FPGA aborts the configuration operation.

After configuration, these pins are available as general-purpose user I/O. However, the SelectMAP configuration interface is optionally available for debugging and dynamic reconfiguration. To use these SelectMAP pins after configuration, set the Persist bitstream generation option.

The Readback debugging option, for example, requires the Persist bitstream generation option. During Readback mode, assert CS_B Low, along with RDWR_B High, to read a configuration data byte from the FPGA to the D0-D7 bus on a rising CCLK edge. During Readback mode, D0-D7 are output pins.

In all the cases, the configuration data and control signals are synchronized to the rising edge of the CCLK clock signal.

Table 72: Dual-Purpose Configuration Pins for Parallel (SelectMAP) Configuration Modes

Pin Name	Direction	Description						
D0, D1, D2, D3	<ul style="list-style-type: none">Input during configurationOutput during readback	Configuration Data Port (high nibble): Collectively, the D0-D7 pins are the byte-wide configuration data port for the Parallel (SelectMAP) configuration modes. Configuration data is synchronized to the rising edge of CCLK clock signal. The D0-D3 pins are the high nibble of the configuration data byte and located in Bank 4 and powered by VCCO_4. The BitGen option Persist permits this pin to retain its configuration function in the User mode.						
D4, D5, D6, D7	<ul style="list-style-type: none">Input during configurationOutput during readback	Configuration Data Port (low nibble): The D4-D7 pins are the low nibble of the configuration data byte. However, these signals are located in Bank 5 and powered by VCCO_5. The BitGen option Persist permits this pin to retain its configuration function in the User mode.						
CS_B	Input	Chip Select for Parallel Mode Configuration: Assert this pin Low, together with RDWR_B to write a configuration data byte from the D0-D7 bus to the FPGA on a rising CCLK edge. During Readback, assert this pin Low, along with RDWR_B High, to read a configuration data byte from the FPGA to the D0-D7 bus on a rising CCLK edge. This signal is located in Bank 5 and powered by VCCO_5. The BitGen option Persist permits this pin to retain its configuration function in the User mode. <table><tr><th>CS_B</th><th>Function</th></tr><tr><td>0</td><td>FPGA selected. SelectMAP inputs are valid on the next rising edge of CCLK.</td></tr><tr><td>1</td><td>FPGA deselected. All SelectMAP inputs are ignored.</td></tr></table>	CS_B	Function	0	FPGA selected. SelectMAP inputs are valid on the next rising edge of CCLK.	1	FPGA deselected. All SelectMAP inputs are ignored.
CS_B	Function							
0	FPGA selected. SelectMAP inputs are valid on the next rising edge of CCLK.							
1	FPGA deselected. All SelectMAP inputs are ignored.							
RDWR_B	Input	Read/Write Control for Parallel Mode Configuration: In Master and Slave Parallel modes, assert this pin Low together with CS_B to write a configuration data byte from the D0-D7 bus to the FPGA on a rising CCLK edge. Once asserted during configuration, RDWR_B must remain asserted until configuration is complete. During Readback, assert this pin High with CS_B Low to read a configuration data byte from the FPGA to the D0-D7 bus on a rising CCLK edge. This signal is located in Bank 5 and powered by VCCO_5. The BitGen option Persist permits this pin to retain its configuration function in the User mode. <table><tr><th>RDWR_B</th><th>Function</th></tr><tr><td>0</td><td>If CS_B is Low, then load (write) configuration data to the FPGA.</td></tr><tr><td>1</td><td>This option is valid only if the Persist bitstream option is set to Yes. If CS_B is Low, then read configuration data from the FPGA.</td></tr></table>	RDWR_B	Function	0	If CS_B is Low, then load (write) configuration data to the FPGA.	1	This option is valid only if the Persist bitstream option is set to Yes. If CS_B is Low, then read configuration data from the FPGA.
RDWR_B	Function							
0	If CS_B is Low, then load (write) configuration data to the FPGA.							
1	This option is valid only if the Persist bitstream option is set to Yes. If CS_B is Low, then read configuration data from the FPGA.							

Table 87: VQ100 Package Pinout (Cont'd)

Bank	XC3S50 XC3S200 Pin Name	VQ100 Pin Number	Type
2	IO_L40N_2	P65	I/O
2	IO_L40P_2/VREF_2	P64	VREF
2	VCCO_2	P70	VCCO
3	IO	P55	I/O
3	IO	P59	I/O
3	IO_L01N_3/VRP_3	P54	DCI
3	IO_L01P_3/VRN_3	P53	DCI
3	IO_L24N_3	P61	I/O
3	IO_L24P_3	P60	I/O
3	IO_L40N_3/VREF_3	P63	VREF
3	IO_L40P_3	P62	I/O
3	VCCO_3	P57	VCCO
4	IO_L01N_4/VRP_4	P50	DCI
4	IO_L01P_4/VRN_4	P49	DCI
4	IO_L27N_4/DIN/D0	P48	DUAL
4	IO_L27P_4/D1	P47	DUAL
4	IO_L30N_4/D2	P44	DUAL
4	IO_L30P_4/D3	P43	DUAL
4	IO_L31N_4/INIT_B	P42	DUAL
4	IO_L31P_4/DOOUT/BUSY	P40	DUAL
4	IO_L32N_4/GCLK1	P39	GCLK
4	IO_L32P_4/GCLK0	P38	GCLK
4	VCCO_4	P46	VCCO
5	IO_L01N_5/RDWR_B	P28	DUAL
5	IO_L01P_5/CS_B	P27	DUAL
5	IO_L28N_5/D6	P32	DUAL
5	IO_L28P_5/D7	P30	DUAL
5	IO_L31N_5/D4	P35	DUAL
5	IO_L31P_5/D5	P34	DUAL
5	IO_L32N_5/GCLK3	P37	GCLK
5	IO_L32P_5/GCLK2	P36	GCLK
5	VCCO_5	P31	VCCO
6	IO	P17	I/O
6	IO	P21	I/O
6	IO_L01N_6/VRP_6	P23	DCI
6	IO_L01P_6/VRN_6	P22	DCI
6	IO_L24N_6/VREF_6	P16	VREF
6	IO_L24P_6	P15	I/O
6	IO_L40N_6	P14	I/O

Table 96: FT256 Package Pinout (Cont'd)

Bank	XC3S200, XC3S400, XC3S1000 Pin Name	FT256 Pin Number	Type
7	IO_L24P_7	G4	I/O
7	IO_L39N_7	H3	I/O
7	IO_L39P_7	H4	I/O
7	IO_L40N_7/VREF_7	H1	VREF
7	IO_L40P_7	G1	I/O
7	VCCO_7	G6	VCCO
7	VCCO_7	H5	VCCO
7	VCCO_7	H6	VCCO
N/A	GND	A1	GND
N/A	GND	A16	GND
N/A	GND	B2	GND
N/A	GND	B9	GND
N/A	GND	B15	GND
N/A	GND	F6	GND
N/A	GND	F11	GND
N/A	GND	G7	GND
N/A	GND	G8	GND
N/A	GND	G9	GND
N/A	GND	G10	GND
N/A	GND	H2	GND
N/A	GND	H7	GND
N/A	GND	H8	GND
N/A	GND	H9	GND
N/A	GND	H10	GND
N/A	GND	J7	GND
N/A	GND	J8	GND
N/A	GND	J9	GND
N/A	GND	J10	GND
N/A	GND	J15	GND
N/A	GND	K7	GND
N/A	GND	K8	GND
N/A	GND	K9	GND
N/A	GND	K10	GND
N/A	GND	L6	GND
N/A	GND	L11	GND
N/A	GND	R2	GND
N/A	GND	R8	GND
N/A	GND	R15	GND
N/A	GND	T1	GND

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
0	IO_L30N_0	IO_L30N_0	G15	I/O
0	IO_L30P_0	IO_L30P_0	F15	I/O
0	IO_L31N_0	IO_L31N_0	D15	I/O
0	IO_L31P_0/VREF_0	IO_L31P_0/VREF_0	C15	VREF
0	IO_L32N_0/GCLK7	IO_L32N_0/GCLK7	B15	GCLK
0	IO_L32P_0/GCLK6	IO_L32P_0/GCLK6	A15	GCLK
0	N.C. (◆)	IO_L35N_0	B7	I/O
0	N.C. (◆)	IO_L35P_0	A7	I/O
0	N.C. (◆)	IO_L36N_0	G7	I/O
0	N.C. (◆)	IO_L36P_0	H8	I/O
0	N.C. (◆)	IO_L37N_0	E9	I/O
0	N.C. (◆)	IO_L37P_0	D9	I/O
0	N.C. (◆)	IO_L38N_0	B9	I/O
0	N.C. (◆)	IO_L38P_0	A9	I/O
0	VCCO_0	VCCO_0	C5	VCCO
0	VCCO_0	VCCO_0	E7	VCCO
0	VCCO_0	VCCO_0	C9	VCCO
0	VCCO_0	VCCO_0	G9	VCCO
0	VCCO_0	VCCO_0	J11	VCCO
0	VCCO_0	VCCO_0	L12	VCCO
0	VCCO_0	VCCO_0	C13	VCCO
0	VCCO_0	VCCO_0	G13	VCCO
0	VCCO_0	VCCO_0	L13	VCCO
0	VCCO_0	VCCO_0	L14	VCCO
1	IO	IO	E25	I/O
1	IO	IO	J21	I/O
1	IO	IO	K20	I/O
1	IO	IO	F18	I/O
1	IO	IO	F16	I/O
1	IO	IO	A16	I/O
1	IO/VREF_1	IO/VREF_1	J17	VREF
1	IO_L01N_1/VRP_1	IO_L01N_1/VRP_1	A27	DCI
1	IO_L01P_1/VRN_1	IO_L01P_1/VRN_1	B27	DCI
1	IO_L02N_1	IO_L02N_1	D26	I/O
1	IO_L02P_1	IO_L02P_1	C27	I/O
1	IO_L03N_1	IO_L03N_1	A26	I/O
1	IO_L03P_1	IO_L03P_1	B26	I/O
1	IO_L04N_1	IO_L04N_1	B25	I/O
1	IO_L04P_1	IO_L04P_1	C25	I/O
1	IO_L05N_1	IO_L05N_1	F24	I/O

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
2	IO_L28N_2	IO_L28N_2	M26	I/O
2	IO_L28P_2	IO_L28P_2	N25	I/O
2	IO_L29N_2	IO_L29N_2	N26	I/O
2	IO_L29P_2	IO_L29P_2	N27	I/O
2	IO_L31N_2	IO_L31N_2	N29	I/O
2	IO_L31P_2	IO_L31P_2	N30	I/O
2	IO_L32N_2	IO_L32N_2	P21	I/O
2	IO_L32P_2	IO_L32P_2	P22	I/O
2	IO_L33N_2	IO_L33N_2	P24	I/O
2	IO_L33P_2	IO_L33P_2	P25	I/O
2	IO_L34N_2/VREF_2	IO_L34N_2/VREF_2	P28	VREF
2	IO_L34P_2	IO_L34P_2	P29	I/O
2	IO_L35N_2	IO_L35N_2	R21	I/O
2	IO_L35P_2	IO_L35P_2	R22	I/O
2	IO_L37N_2	IO_L37N_2	R23	I/O
2	IO_L37P_2	IO_L37P_2	R24	I/O
2	IO_L38N_2	IO_L38N_2	R25	I/O
2	IO_L38P_2	IO_L38P_2	R26	I/O
2	IO_L39N_2	IO_L39N_2	R27	I/O
2	IO_L39P_2	IO_L39P_2	R28	I/O
2	IO_L40N_2	IO_L40N_2	R29	I/O
2	IO_L40P_2/VREF_2	IO_L40P_2/VREF_2	R30	VREF
2	N.C. (◆)	IO_L41N_2	E27	I/O
2	N.C. (◆)	IO_L41P_2	F26	I/O
2	N.C. (◆)	IO_L45N_2	K28	I/O
2	N.C. (◆)	IO_L45P_2	K29	I/O
2	N.C. (◆)	IO_L46N_2	K21	I/O
2	N.C. (◆)	IO_L46P_2	L21	I/O
2	N.C. (◆)	IO_L47N_2	L23	I/O
2	N.C. (◆)	IO_L47P_2	L24	I/O
2	N.C. (◆)	IO_L50N_2	M29	I/O
2	N.C. (◆)	IO_L50P_2	M30	I/O
2	VCCO_2	VCCO_2	M20	VCCO
2	VCCO_2	VCCO_2	N20	VCCO
2	VCCO_2	VCCO_2	P20	VCCO
2	VCCO_2	VCCO_2	L22	VCCO
2	VCCO_2	VCCO_2	J24	VCCO
2	VCCO_2	VCCO_2	N24	VCCO
2	VCCO_2	VCCO_2	G26	VCCO
2	VCCO_2	VCCO_2	E28	VCCO

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
6	IO_L28P_6	IO_L28P_6	W1	I/O
6	IO_L29N_6	IO_L29N_6	W10	I/O
6	IO_L29P_6	IO_L29P_6	V10	I/O
6	N.C. (◆)	IO_L30N_6	V9	I/O
6	N.C. (◆)	IO_L30P_6	V8	I/O
6	IO_L31N_6	IO_L31N_6	W5	I/O
6	IO_L31P_6	IO_L31P_6	V6	I/O
6	IO_L32N_6	IO_L32N_6	V5	I/O
6	IO_L32P_6	IO_L32P_6	V4	I/O
6	IO_L33N_6	IO_L33N_6	V2	I/O
6	IO_L33P_6	IO_L33P_6	V1	I/O
6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	U10	VREF
6	IO_L34P_6	IO_L34P_6	U9	I/O
6	IO_L35N_6	IO_L35N_6	U7	I/O
6	IO_L35P_6	IO_L35P_6	U6	I/O
6	N.C. (◆)	IO_L36N_6	U3	I/O
6	N.C. (◆)	IO_L36P_6	U2	I/O
6	IO_L37N_6	IO_L37N_6	T10	I/O
6	IO_L37P_6	IO_L37P_6	T9	I/O
6	IO_L38N_6	IO_L38N_6	T6	I/O
6	IO_L38P_6	IO_L38P_6	T5	I/O
6	IO_L39N_6	IO_L39N_6	T4	I/O
6	IO_L39P_6	IO_L39P_6	T3	I/O
6	IO_L40N_6	IO_L40N_6	T2	I/O
6	IO_L40P_6/VREF_6	IO_L40P_6/VREF_6	T1	VREF
6	N.C. (◆)	IO_L45N_6	Y4	I/O
6	N.C. (◆)	IO_L45P_6	Y3	I/O
6	N.C. (◆)	IO_L52N_6	T8	I/O
6	N.C. (◆)	IO_L52P_6	T7	I/O
6	VCCO_6	VCCO_6	V3	VCCO
6	VCCO_6	VCCO_6	AB3	VCCO
6	VCCO_6	VCCO_6	AF3	VCCO
6	VCCO_6	VCCO_6	AD5	VCCO
6	VCCO_6	VCCO_6	V7	VCCO
6	VCCO_6	VCCO_6	AB7	VCCO
6	VCCO_6	VCCO_6	Y9	VCCO
6	VCCO_6	VCCO_6	U11	VCCO
6	VCCO_6	VCCO_6	V11	VCCO
6	VCCO_6	VCCO_6	W11	VCCO
7	IO	IO	J6	I/O

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
6	IO_L16N_6	IO_L16N_6	AE2	I/O
6	IO_L16P_6	IO_L16P_6	AE1	I/O
6	IO_L17N_6	IO_L17N_6	AD10	I/O
6	IO_L17P_6/VREF_6	IO_L17P_6/VREF_6	AD9	VREF
6	IO_L19N_6	IO_L19N_6	AD2	I/O
6	IO_L19P_6	IO_L19P_6	AD1	I/O
6	IO_L20N_6	IO_L20N_6	AC11	I/O
6	IO_L20P_6	IO_L20P_6	AC10	I/O
6	IO_L21N_6	IO_L21N_6	AC8	I/O
6	IO_L21P_6	IO_L21P_6	AC7	I/O
6	IO_L22N_6	IO_L22N_6	AC6	I/O
6	IO_L22P_6	IO_L22P_6	AC5	I/O
6	IO_L23N_6	IO_L23N_6	AC2	I/O
6	IO_L23P_6	IO_L23P_6	AC1	I/O
6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	AC9	VREF
6	IO_L24P_6	IO_L24P_6	AB10	I/O
6	IO_L25N_6	IO_L25N_6	AB8	I/O
6	IO_L25P_6	IO_L25P_6	AB7	I/O
6	IO_L26N_6	IO_L26N_6	AB4	I/O
6	IO_L26P_6	IO_L26P_6	AB3	I/O
6	IO_L27N_6	IO_L27N_6	AB11	I/O
6	IO_L27P_6	IO_L27P_6	AA11	I/O
6	IO_L28N_6	IO_L28N_6	AA8	I/O
6	IO_L28P_6	IO_L28P_6	AA7	I/O
6	IO_L29N_6	IO_L29N_6	AA6	I/O
6	IO_L29P_6	IO_L29P_6	AA5	I/O
6	IO_L30N_6	IO_L30N_6	AA4	I/O
6	IO_L30P_6	IO_L30P_6	AA3	I/O
6	IO_L31N_6	IO_L31N_6	AA2	I/O
6	IO_L31P_6	IO_L31P_6	AA1	I/O
6	IO_L32N_6	IO_L32N_6	Y11	I/O
6	IO_L32P_6	IO_L32P_6	Y10	I/O
6	IO_L33N_6	IO_L33N_6	Y4	I/O
6	IO_L33P_6	IO_L33P_6	Y3	I/O
6	IO_L34N_6/VREF_6	IO_L34N_6/VREF_6	Y2	VREF
6	IO_L34P_6	IO_L34P_6	Y1	I/O
6	IO_L35N_6	IO_L35N_6	Y9	I/O
6	IO_L35P_6	IO_L35P_6	W10	I/O
6	IO_L36N_6	IO_L36N_6	W7	I/O
6	IO_L36P_6	IO_L36P_6	W6	I/O

Date	Version	Description
11/30/07	2.3	Added XC3S5000 FG(G)676 package. Noted that the FG(G)1156 package is being discontinued. Updated Table 86 with latest thermal characteristics data.
06/25/08	2.4	Updated formatting and links.
12/04/09	2.5	Added link to UG332 in CCLK: Configuration Clock . Noted that the CP132, CPG132, FG1156, and FGG1156 packages are being discontinued in Table 81 , Table 83 , Table 84 , Table 85 , and Table 86 . Updated CP132: 132-Ball Chip-Scale Package to indicate that the CP132 and CPG132 packages are being discontinued.
10/29/12	3.0	Added Notice of Disclaimer . Per XCN07022 , updated the FG1156 and FGG1156 package discussion throughout document including in Table 81 , Table 83 , Table 84 , Table 85 , and Table 86 . Per XCN08011 , updated CP132 and CPG132 package discussion throughout document including in Table 81 , Table 83 , Table 84 , Table 85 , and Table 86 . This product is not recommended for new designs.

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